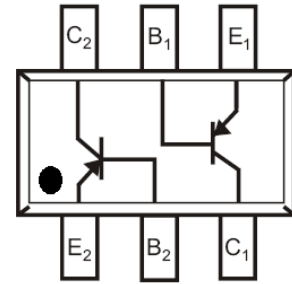


### Features

- Epitaxial planar die construction
- Ideal for low power amplification and switching
- Ultra-small surface mount package

HF



SOT-563

### Mechanical Data

- Case: SOT-563
- Molding compound: UL flammability classification rating 94V-0
- Terminal s: Tin-plated; solderability per MIL-STD-202, Method 208

### Ordering Information

Part Number	Package	Shipping Quantity	Marking Code
MMDT3906V	SOT-563	3000pcs / Tape & Reel	KAR

### Maximum Ratings (@ T<sub>A</sub> = 25°C unless otherwise specified)

Parameter	Symbol	Value	Unit
Collector-Base Breakdown Voltage	V <sub>CBO</sub>	-40	V
Collector-Emitter Breakdown Voltage	V <sub>CEO</sub>	-40	V
Emitter-Base Breakdown Voltage	V <sub>EBO</sub>	-5	V
Collector Current (Continuous)	I <sub>C</sub>	-0.2	A

### Thermal Characteristics

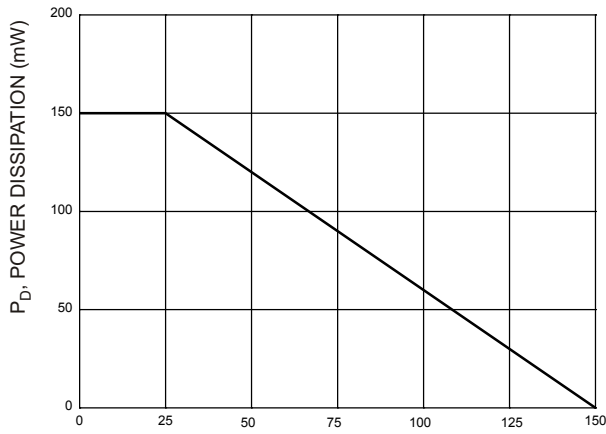
Parameter	Symbol	Value	Unit
Power Dissipation (Collector) <sup>*1</sup>	P <sub>C</sub>	150	mW
Thermal Resistance (Junction-to-Ambient) <sup>*1</sup>	R <sub>θJA</sub>	833	°C/W
Junction Temperature	T <sub>J</sub>	-55 ~ +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 ~ +150	°C

Note 1: Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch.

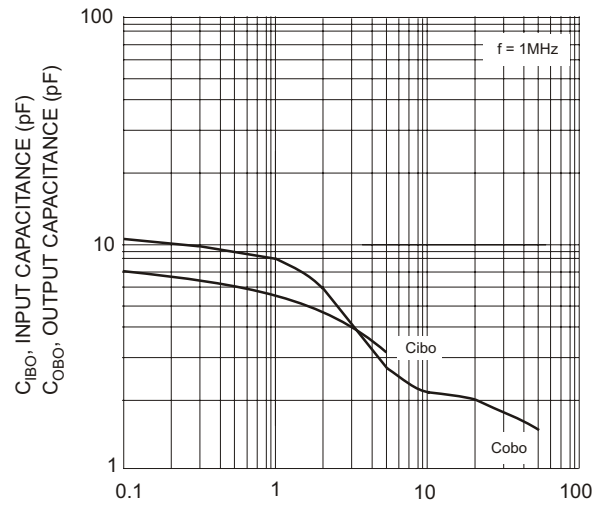
**Electrical Characteristics** (@  $T_A = 25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Collector-Base Breakdown Voltage	$V_{(BR)CBO}$	$I_C = -10\mu\text{A}, I_E = 0$	-40	-	-	V
Collector-Emitter Breakdown Voltage	$V_{(BR)CEO}$	$I_C = -1\text{mA}, I_B = 0$	-40	-	-	V
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	$I_E = -10\mu\text{A}, I_C = 0$	-5	-	-	V
Collector Cut-off Current	$I_{CEX}$	$V_{CE} = -30\text{V}, V_{EB(OFF)} = -3.0\text{V}$	-	-	-50	nA
Base Cut-off Current	$I_{BL}$	$V_{CE} = -30\text{V}, V_{EB(OFF)} = -3.0\text{V}$	-	-	-50	nA
DC Current Gain	$h_{FE}$	$V_{CE} = -1\text{V}, I_C = -0.1\text{mA}$	60	-	-	-
		$V_{CE} = -1\text{V}, I_C = -1\text{mA}$	80	-	-	-
		$V_{CE} = -1\text{V}, I_C = -10\text{mA}$	100	-	300	-
		$V_{CE} = -1\text{V}, I_C = -50\text{mA}$	60	-	-	-
		$V_{CE} = -1\text{V}, I_C = -100\text{mA}$	30	-	-	-
Collector-emitter Saturation Voltage	$V_{CE(sat)}$	$I_C = -10\text{mA}, I_B = -1\text{mA}$	-	-	-0.25	V
		$I_C = -50\text{mA}, I_B = -5\text{mA}$	-	-	-0.4	V
Base-emitter Saturation Voltage	$V_{BE(sat)}$	$I_C = -10\text{mA}, I_B = -1\text{mA}$	-0.65	-	-0.85	V
		$I_C = -50\text{mA}, I_B = -5\text{mA}$	-	-	-0.95	V
Output Capacitance	$C_{OBO}$	$V_{CB} = -5\text{V}, I_E = 0\text{A}, f = 1\text{MHz}$	-	-	4.5	pF
Input Capacitance	$C_{IBO}$	$I_C = 0, V_{EB} = -0.5\text{V}, f = 1\text{MHz}$	-	-	10	pF
Transition Frequency	$f_T$	$I_C = -1\text{mA}, V_{CE} = -10\text{V}$ $f = 1\text{KHz}$	250	-	-	MHZ
Noise Figure	NF	$I_C = -0.1\text{mA}, V_{CE} = -20\text{V}$ $f = 100\text{MHz}$	-	-	4	dB
Delay Time	$t_d$	$V_{CC} = -3\text{V}, V_{BE(off)} = 0.5\text{V}$	-	-	35	ns
Rise Time	$t_r$	$I_C = -10\text{mA}, I_{B1} = -1\text{mA}$	-	-	35	ns
Storage Time	$t_s$	$V_{CC} = -3\text{V}, I_C = -10\text{mA}$	-	-	225	ns
Fall Time	$t_f$	$I_{B1} = I_{B2} = -1\text{mA}$	-	-	75	ns

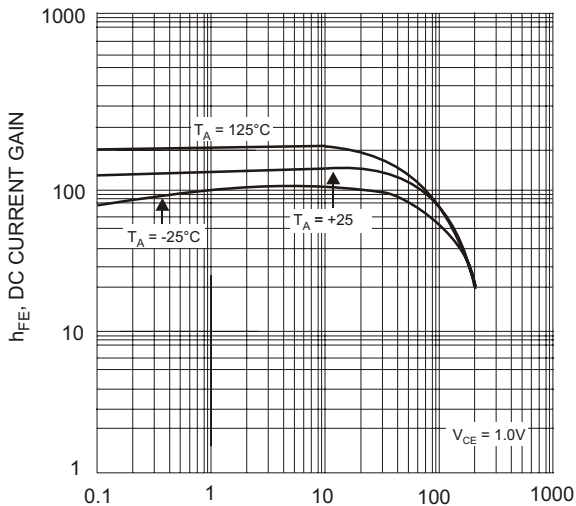
### Ratings and Characteristic Curves ( $T_A=25^\circ\text{C}$ unless otherwise noted)



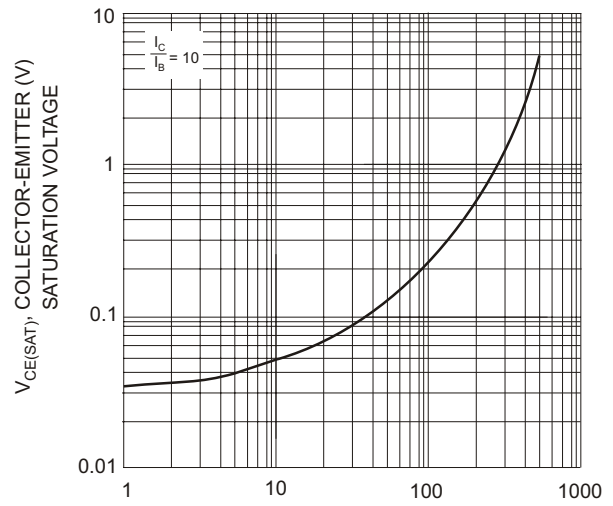
$T_A$ , AMBIENT TEMPERATURE ( $^\circ\text{C}$ )  
 Fig. 1, Max Power Dissipation vs Ambient Temperature



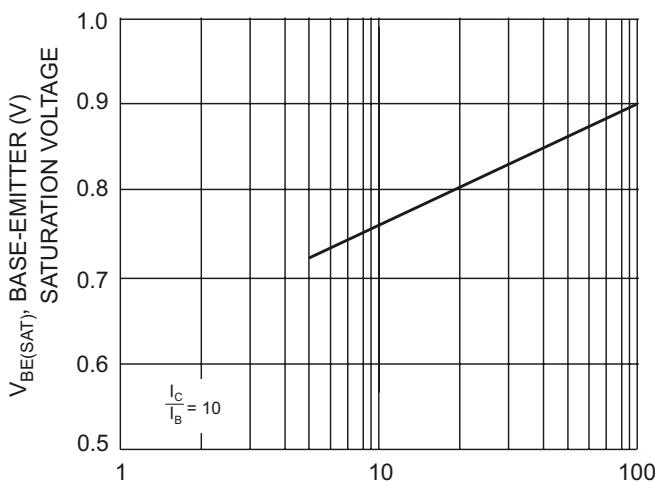
$V_{CB}$ , COLLECTOR-BASE VOLTAGE (V)  
 Fig. 2, Input and Output Capacitance vs. Collector-Base Voltage



$I_C$ , COLLECTOR CURRENT (mA)  
 Fig. 3, Typical DC Current Gain vs Collector Current

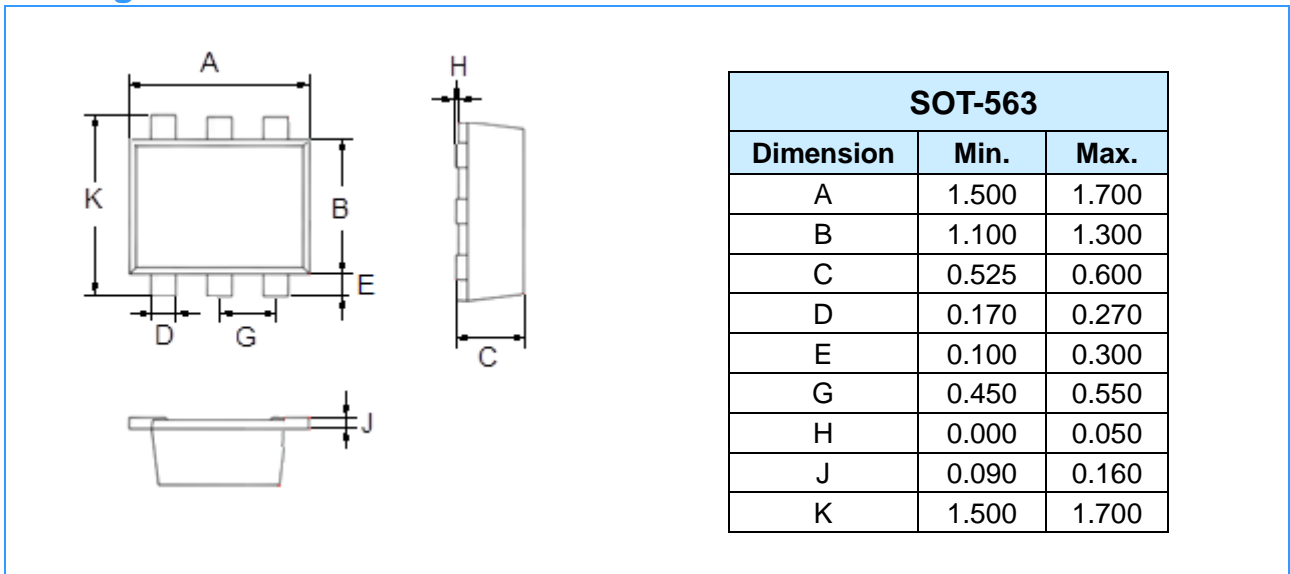


$I_C$ , COLLECTOR CURRENT (mA)  
 Fig. 4, Typical Collector-Emitter Saturation Voltage vs. Collector Current

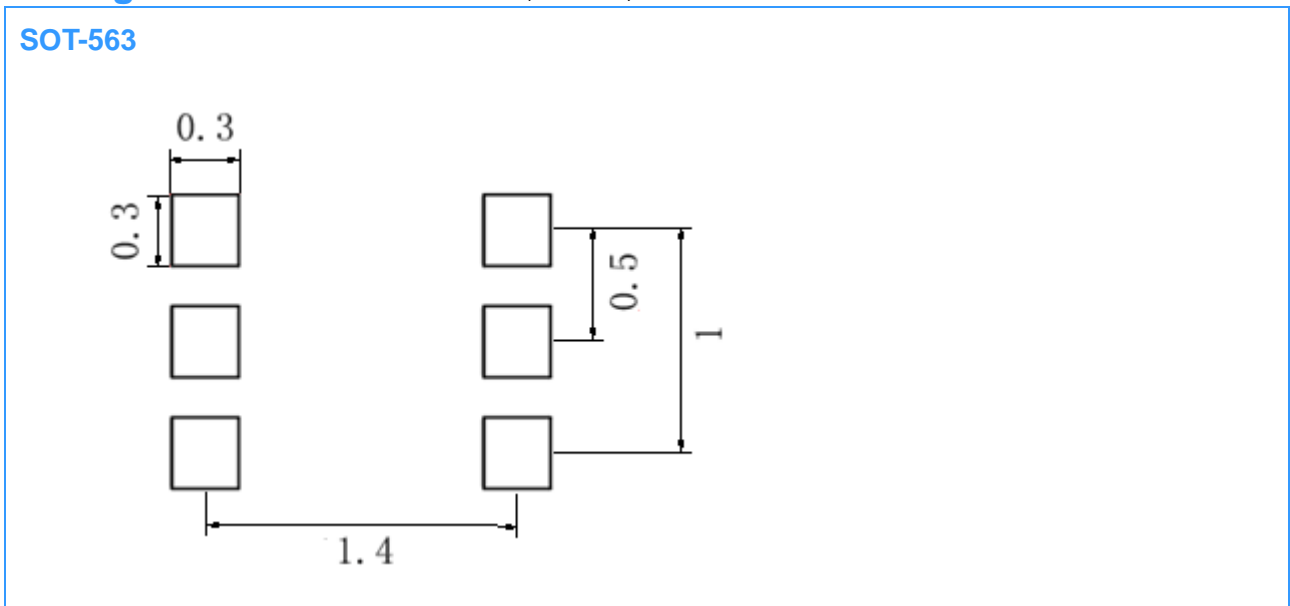


$I_C$ , COLLECTOR CURRENT (mA)  
 Fig. 5, Typical Base-Emitter Saturation Voltage vs. Collector Current

Package Outline Dimensions (Unit: mm)



Package Outline Dimensions (Unit: mm)



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